Lattice Semiconductor Corporation - LFSCM3GA15EP1-5FN256I Datasheet

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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3750
Number of Logic Elements/Cells	15000
Total RAM Bits	1054720
Number of I/O	139
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga15ep1-5fn256i

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM and ROM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SPR 16x2 DPR 16x2	ROM 16x2

Logic Mode

In this mode, the LUTs in each Slice are configured as combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other Slices in the PFU.

Ripple Mode

Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Up counter 2-bit
- Down counter 2-bit
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Ripple Mode includes an optional configuration that performs arithmetic using fast carry chain methods. In this configuration (also referred to as CCU2 mode) two additional signals, Carry Generate and Carry Propagate, are generated on a per slice basis to allow fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode

In this mode, distributed RAM can be constructed using each LUT block as a 16x1-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the Slice. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

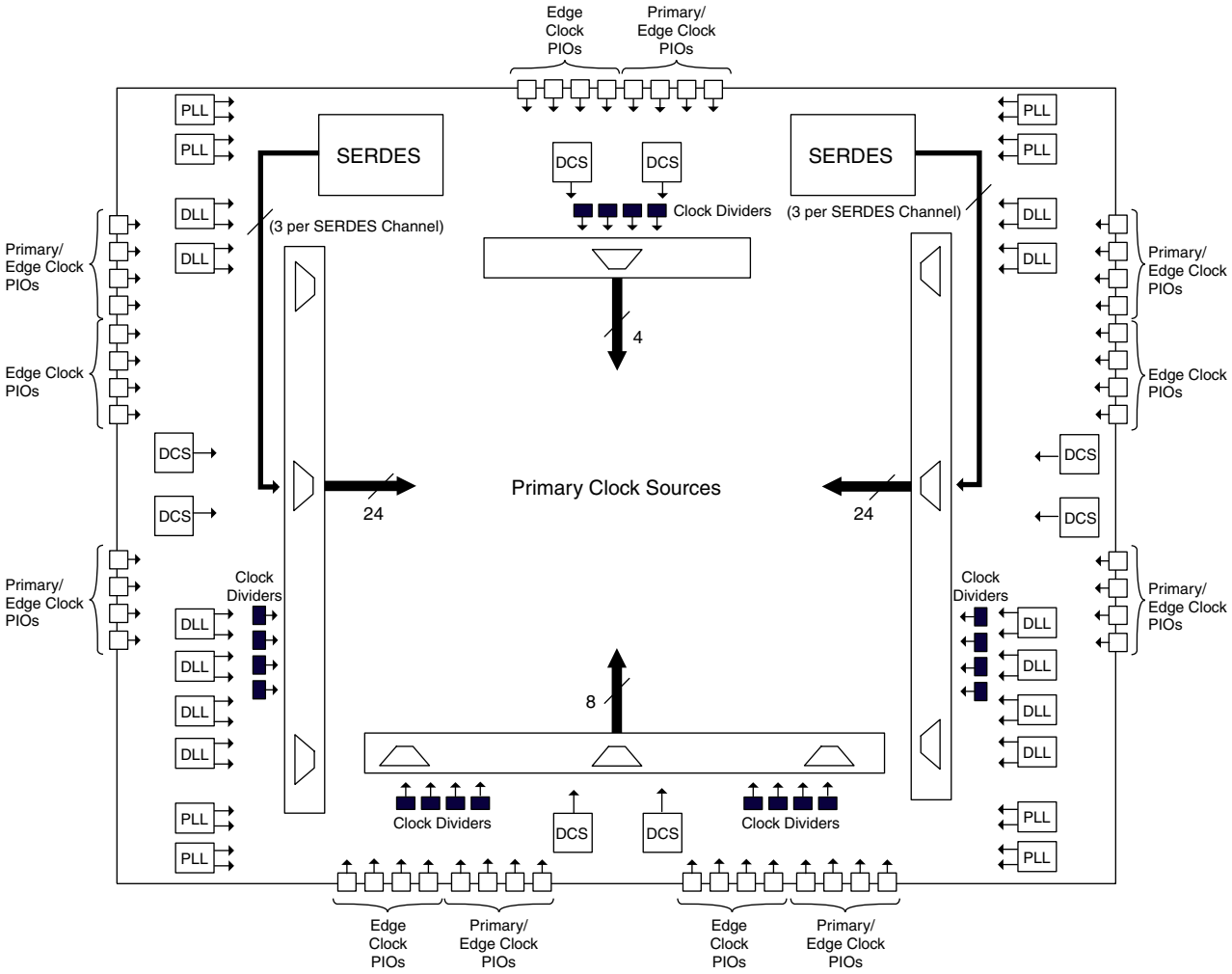
ROM Mode

The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

- Two outputs per PLL
- Clock divider outputs
- Digital Clock Select (DCS) block outputs
- Three outputs per SERDES quad

Figure 2-5 shows the arrangement of the primary clock sources.

Figure 2-5. Clock Sources



Primary Clock Routing

The clock routing structure in LatticeSC devices consists of 12 Primary Clock lines per quadrant. The primary clocks are generated from 64:1 MUXs located in each quadrant. Three of the inputs to each 64:1 MUX comes from local routing, one is connected to GND and rest of the 60 inputs are from the primary clock sources. Figure 2-6 shows this clock routing.

3. **Bottom Side (Banks 4 and 5)**
   These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but true HLVDS and RSDS differential drivers are not available. Adaptive input logic is available on PIOs A or C.

Table 2-8 lists the standards supported by each side.

Table 2-8. I/O Standards Supported by Different Banks

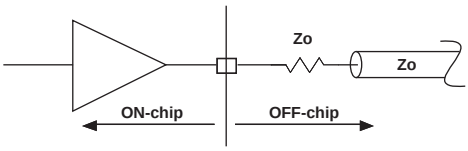
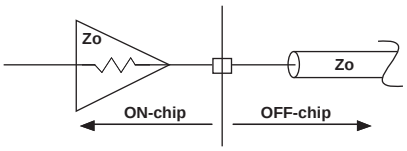
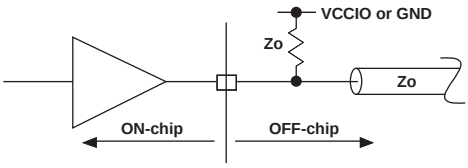
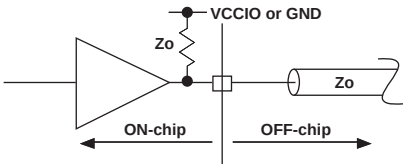
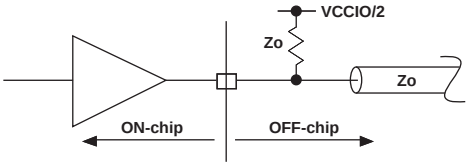
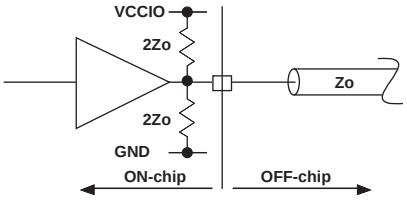
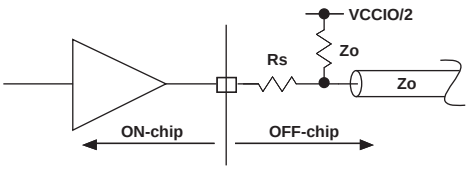
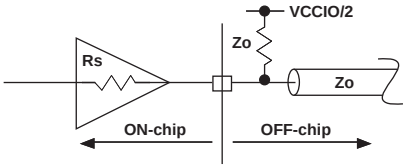
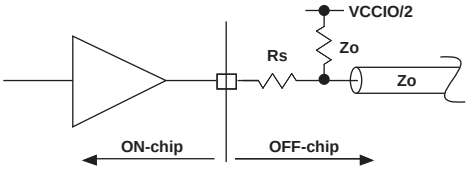
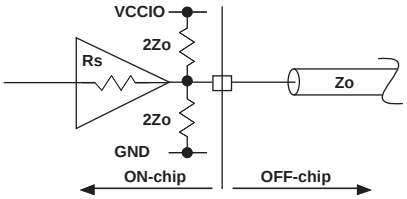
Description	Top Side Banks 1	Right Side Banks 2-3	Bottom Side Banks 4-5	Left Side Banks 6-7
I/O Buffer Type	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver
Output Standards Supported	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II SSTL33_ I, II HSTL15_I, II, III[1], IV[1] HSTL18_I, II,III[1], IV[1] SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL[2], GTL+[2]	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_ I, II HSTL15_I,III HSTL18_I,II,III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL[2], GTL+[2]
Input Standards Supported	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Clock Inputs	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Differential Output Support via Emulation	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL
AIL Support	No	Yes	Yes	Yes

1. Input only.
2. Input only. Outputs supported by bussing multiple outputs together.

Supported Standards

The LatticeSC PURESPEED I/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 12, 15, 18, 25 and 33 standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, termination resistance, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL, HSTL, GTL (input only), GTL+ (input only), PCI33, PCIX33, PCIX15, AGP-1X33 and AGP-2X33. Differential standards supported include LVDS, RSDS, BLVDS, MLVDS, LVPECL, differential SSTL and differential HSTL. Tables 12 and 13 show the I/O standards (together with their supply and reference voltages) supported by the LatticeSC devices. The tables also provide the available internal termination schemes. For further information on utilizing the PURESPEED I/O buffer to support a variety of standards please see details of additional technical documentation at the end of this data sheet.

Figure 2-27. Output Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Series termination (controlled output impedance)		
Parallel termination to V_{CCIO}, or parallel driving end		
Parallel termination to $V_{CCIO}/2$ driving end		
Combined series + parallel termination to $V_{CCIO}/2$ at driving end (only series termination moved on-chip)		
Combined series + parallel to $V_{CCIO}/2$ driving end		

Switching Characteristics

All devices are 100% functionally tested. Listed below are representative values of internal and external timing parameters. For more specific, more precise, and worst-case guaranteed data at a particular temperature and voltage, use the values reported by the static timing analyzer in the ispLEVER design tool from Lattice and back-annotate to the simulation net list.

Figure 3-8. Read Mode with Input and Output Registers

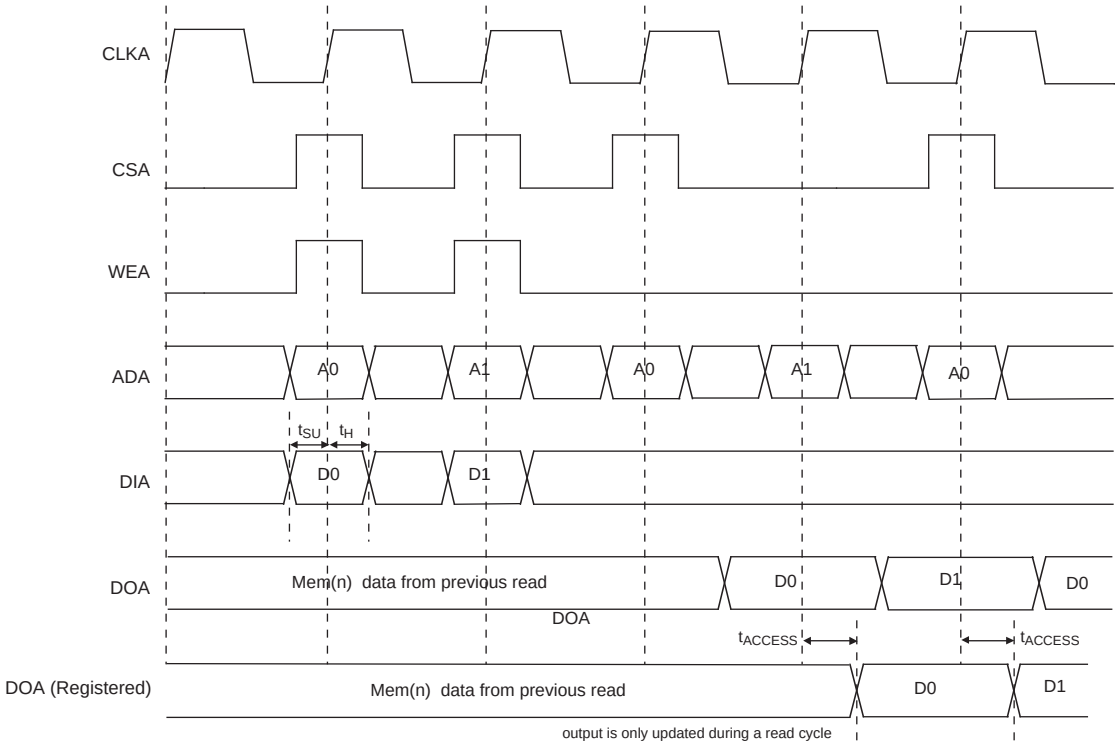
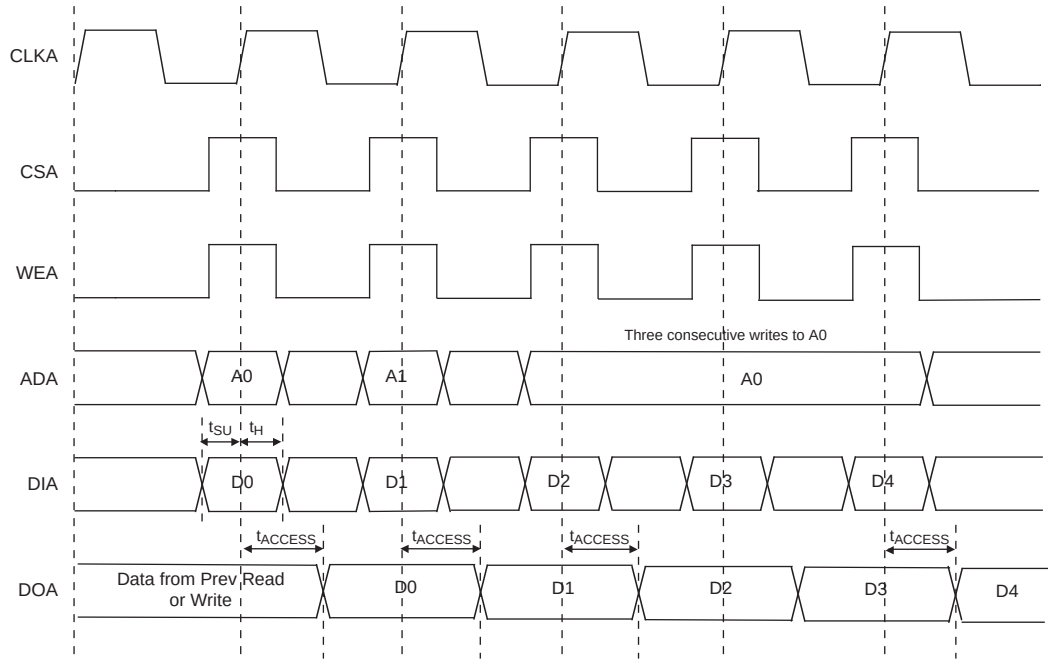


Figure 3-9. Write Through (SP Read/Write On Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
D[n:0]	I/O	In parallel configuration modes, D[7:0] receives configuration data, and each pin is pull-up enabled. For slave serial mode, D0 is the data input. D[7:3] is the output internal status for peripheral mode when RDN is low. D[7:0] is also the first byte of MPI data pins. In MPI configuration mode, MPI selectable data bus width from 8 and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
DP[m:0]	I/O	MPI selectable parity data bus width from 1, 2, and 3-bit DP[0] for D[7:0], DP[1] for D[15:8], and DP[2] for D[23:16].
BUSYN/RCLK/SCK	O	During configuration in peripheral mode, high on BUSYN indicates another byte can be written to the FPGA. If a read operation is done when the device is selected, the same status is also available on D[7] in asynchronous peripheral mode. During configuration in slave parallel mode, low on BUSYN inhibits the external host from sending new data. The output is used by slave parallel and master serial modes only for decompression. During configuration in master parallel and master byte modes, RCLK is a read clock output signal to an external memory. The RCLK frequency is the same as CCLK when used with uncompressed bitstreams. RCLK will be 1/8 the frequency of CCLK when the bitstream is compressed. During configuration in SPI modes, SCK is generated by the device and connected to the CLK input of the FLASH memory.
MPI Interface (Dedicated pin)		
MPI_IRQ_N	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
MPI Interface (User I/O if MPI is not used.)		
MPI_CS0N MPI_CS1	I	MPI chip select pins, active low on MPI_CS0N while active high on MPI_CS1. Both have to be active during the whole transfer data phase. During transfer address phase, both can be inactive so that the decoding for them from address can be slow. If they are active during address phase, one cycle can be saved for sync read.
MPI_CLK	I	This is the PowerPC bus clock. It can be a source of the clock for embedded system bus. If MPI_CLK is used as system bus clock, MPI will be set into sync mode by default. All of the operation on PowerPC side of MPI are synchronized to the rising edge of this clock.
MPI_TSIZ[1:0]	I	Driven by a bus master to indicate the data transfer size for the transaction. 01 for byte, 10 for half-word, and 00 for word.
MPI_WR_N	I	Driven high indicates that a read access is in progress. Driven low indicates that a write access is in process.
MPI_BURST	I	Driven active low indicates that a burst transfer is in progress. Driven high indicates that the current transfer is not a burst.
MPI_BDIP	I	Active low “Burst Data in Process” is driven by a PowerPC processor. Asserted indicates that the second beat in front of the current one is requested by the master. Negated before the burst transfer ends to abort the burst data phase.

Pin Information Summary

Pin Type		256 fpBGA	900 fpBGA		1020 fcBGA	
		LFSC/M15	LFSC/M15	LFSC/M25	LFSC/M25	LFSC/M40
Single Ended User I/O		139	300	378	476	562
Differential Pair User I/O		60	141	182	235	277
LVDS Output Pairs		22	44	60	60	78
Configuration	Dedicated	9	11	11	11	11
	Muxes/MPI sysBus	0	55	55	55	72
JTAG (excluding VCCJ)		4	4	4	4	4
Dedicated Pins		2	4	4	4	4
VCC		10	46	46	40	40
VCC12		10	35	35	36	36
VCCAUX		10	36	36	32	32
VCCIO	Bank 1	3	18	18	10	10
	Bank 2	2	14	14	8	8
	Bank 3	2	15	15	10	10
	Bank 4	3	15	15	10	10
	Bank 5	3	15	15	10	10
	Bank 6	2	15	15	10	10
	Bank 7	2	16	16	8	8
VTT	Bank 2	0	2	2	2	2
	Bank 3	0	3	3	3	3
	Bank 4	0	3	3	3	3
	Bank 5	0	3	3	3	3
	Bank 6	0	3	3	3	3
	Bank 7	0	2	2	2	2
GND		26	177	177	134	134
NC		0	102	24	92	6
Single Ended User / Differential I/O per Bank	Bank 1	21/8	63/30	63/30	68/32	68/32
	Bank 2	15/7	26/13	30/15	34/17	54/27
	Bank 3	19/8	43/20	62/29	84/42	94/47
	Bank 4	25/11	50/22	66/32	84/41	99/48
	Bank 5	25/11	49/23	65/32	88/44	99/49
	Bank 6	19/8	43/20	62/29	84/42	94/47
	Bank 7	15/7	26/13	30/15	34/17	54/27
LVDS Output Pairs Per Bank	Bank 2	5	7	9	9	15
	Bank 3	6	15	21	21	24
	Bank 6	6	15	21	21	24
	Bank 7	5	7	9	9	15
VCCJ		1	1	1	1	1
SERDES (signal + power supply)		28	60	60	108	108
Total		256	900	900	1020	1152

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
J9	VCC	-	
K8	VCC	-	
F6	VCC12	-	
F11	VCC12	-	
L11	VCC12	-	
L6	VCC12	-	
K7	VCC12	-	
K10	VCC12	-	
F10	VCCAUX	-	
F7	VCCAUX	-	
T1	GND	-	
G11	VCCAUX	-	
K11	VCCAUX	-	
L10	VCCAUX	-	
L9	VCCAUX	-	
L7	VCCAUX	-	
L8	VCCAUX	-	
T16	GND	-	
G6	VCCAUX	-	
K6	VCCAUX	-	
B13	VCCIO1	-	
D11	VCCIO1	-	
D14	VCCIO1	-	
F12	VCCIO2	-	
G15	VCCIO2	-	
K14	VCCIO3	-	
N15	VCCIO3	-	
M11	VCCIO4	-	
P13	VCCIO4	-	
R10	VCCIO4	-	
N6	VCCIO5	-	
P7	VCCIO5	-	
R4	VCCIO5	-	
K2	VCCIO6	-	
N3	VCCIO6	-	
F4	VCCIO7	-	
G3	VCCIO7	-	
D4	VCC12	-	
D7	VCC12	-	
D5	VCC12	-	
D6	VCC12	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M15 in a 256-pin package does not support an MPI interface.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH29	PB48B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB68B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AE26	PB48C	4		PB68C	4	
AD25	PB48D	4		PB68D	4	
AJ30	PB49A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B	PB69A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AH30	PB49B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B	PB69B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AG28	PB49C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C	PB69C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AG29	PB49D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C	PB69D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AF26	VCC12	-		VCC12	-	
AD27	PROBE_VCC	-		PROBE_VCC	-	
AG27	VCC12	-		VCC12	-	
AE28	PROBE_GND	-		PROBE_GND	-	
AC25	PR45D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A	PR57D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AD26	PR45C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A	PR57C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A
AF28	PR45B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E	PR57B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AF29	PR45A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E	PR57A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AC26	PR44D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F	PR55D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AB26	PR44C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F	PR55C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AG30	PR44B	3		PR55B	3	
AF30	PR44A	3		PR55A	3	
AC28	PR43B	3		PR52B	3	
AB28	PR43A	3		PR52A	3	
AB27	PR41D	3	VREF2_3	PR51D	3	VREF2_3
AE30	PR41B	3		PR51B	3	
AD30	PR41A	3		PR51A	3	
AB25	PR40B	3		PR49B	3	
AA25	PR40A	3		PR49A	3	
AA30	PR39B	3		PR48B	3	
Y30	PR39A	3		PR48A	3	
W29	PR37B	3		PR44B	3	
V29	PR37A	3		PR44A	3	
U30	PR36B	3		PR43B	3	
T30	PR36A	3		PR43A	3	
V25	PR35D	3	DIFFR_3	PR42D	3	DIFFR_3
W28	PR35B	3		PR42B	3	
V28	PR35A	3		PR42A	3	
R30	PR33B	3		PR38B	3	
P30	PR33A	3		PR38A	3	
N30	PR32B	3		PR35B	3	
M29	PR32A	3		PR35A	3	
U26	PR31D	3		PR34D	3	
T26	PR31C	3	VREF1_3	PR34C	3	VREF1_3
U28	PR31B	3		PR34B	3	
T28	PR31A	3		PR34A	3	
M30	PR28D	3	PCLKC3_2	PR31D	3	PCLKC3_2
L29	PR28C	3	PCLKT3_2	PR31C	3	PCLKT3_2

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AA21	VCCAUX	-		VCCAUX	-	
AA22	VCCAUX	-		VCCAUX	-	
AB11	VCCAUX	-		VCCAUX	-	
AB12	VCCAUX	-		VCCAUX	-	
AB15	VCCAUX	-		VCCAUX	-	
AB16	VCCAUX	-		VCCAUX	-	
AB17	VCCAUX	-		VCCAUX	-	
AB18	VCCAUX	-		VCCAUX	-	
AB21	VCCAUX	-		VCCAUX	-	
AB22	VCCAUX	-		VCCAUX	-	
L11	VCCAUX	-		VCCAUX	-	
L12	VCCAUX	-		VCCAUX	-	
L14	VCCAUX	-		VCCAUX	-	
L15	VCCAUX	-		VCCAUX	-	
L18	VCCAUX	-		VCCAUX	-	
L19	VCCAUX	-		VCCAUX	-	
L21	VCCAUX	-		VCCAUX	-	
L22	VCCAUX	-		VCCAUX	-	
M11	VCCAUX	-		VCCAUX	-	
M12	VCCAUX	-		VCCAUX	-	
M21	VCCAUX	-		VCCAUX	-	
M22	VCCAUX	-		VCCAUX	-	
P11	VCCAUX	-		VCCAUX	-	
P22	VCCAUX	-		VCCAUX	-	
R11	VCCAUX	-		VCCAUX	-	
R22	VCCAUX	-		VCCAUX	-	
V11	VCCAUX	-		VCCAUX	-	
V22	VCCAUX	-		VCCAUX	-	
W11	VCCAUX	-		VCCAUX	-	
W22	VCCAUX	-		VCCAUX	-	
N11	VTT_2	2		VTT_2	2	
R10	VTT_2	2		VTT_2	2	
T11	VTT_3	3		VTT_3	3	
U11	VTT_3	3		VTT_3	3	
Y11	VTT_3	3		VTT_3	3	
AB13	VTT_4	4		VTT_4	4	
AB14	VTT_4	4		VTT_4	4	
AC15	VTT_4	4		VTT_4	4	
AB19	VTT_5	5		VTT_5	5	
AB20	VTT_5	5		VTT_5	5	
AC18	VTT_5	5		VTT_5	5	
T22	VTT_6	6		VTT_6	6	
U22	VTT_6	6		VTT_6	6	
Y22	VTT_6	6		VTT_6	6	
N22	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
M17	VCC12	-		VCC12	-	
M16	VCC12	-		VCC12	-	
T12	VCC12	-		VCC12	-	
T21	VCC12	-		VCC12	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
U12	VCC12	-		VCC12	-	
U21	VCC12	-		VCC12	-	
AA16	VCC12	-		VCC12	-	
AA17	VCC12	-		VCC12	-	
M14	VCC12	-		VCC12	-	
P12	VCC12	-		VCC12	-	
W12	VCC12	-		VCC12	-	
AA14	VCC12	-		VCC12	-	
AA19	VCC12	-		VCC12	-	
W21	VCC12	-		VCC12	-	
P21	VCC12	-		VCC12	-	
M19	VCC12	-		VCC12	-	
A2	GND	-		GND	-	
A10	GND	-		GND	-	
E28	NC	-		NC	-	
E5	NC	-		NC	-	
F10	NC	-		NC	-	
E10	NC	-		NC	-	
E23	NC	-		NC	-	
F23	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M25 and LatticeSC/M40 in a 1020-pin package support a 16-bit MPI interface.

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V25	PL44C	6		PL56C	6	
W25	PL44D	6		PL56D	6	
U34	PL45A	6		PL57A	6	
V34	PL45B	6		PL57B	6	
V26	PL45C	6		PL57C	6	
W26	PL45D	6		PL57D	6	
V33	PL47A	6		PL60A	6	
W33	PL47B	6		PL60B	6	
V24	PL47C	6		PL60C	6	
W24	PL47D	6		PL60D	6	
W31	PL48A	6		PL63A	6	
Y31	PL48B	6		PL63B	6	
Y29	PL48C	6		PL63C	6	
AA29	PL48D	6		PL63D	6	
Y33	PL49A	6		PL65A	6	
AA33	PL49B	6		PL65B	6	
Y28	PL49C	6		PL65C	6	
AA28	PL49D	6		PL65D	6	
AB32	PL51A	6		PL76A	6	
AC32	PL51B	6		PL76B	6	
AA26	PL51C	6		PL76C	6	
AA27	PL51D	6	DIFFR_6	PL76D	6	DIFFR_6
AB31	PL52A	6		PL77A	6	
AC31	PL52B	6		PL77B	6	
Y24	PL52C	6		PL77C	6	
AA24	PL52D	6		PL77D	6	
AE34	PL53A	6		PL78A	6	
AF34	PL53B	6		PL78B	6	
AB30	PL53C	6		PL78C	6	
AC30	PL53D	6		PL78D	6	
AD33	PL56A	6		PL80A	6	
AE33	PL56B	6		PL80B	6	
AD30	PL56C	6		PL80C	6	
AE30	PL56D	6		PL80D	6	
AE32	PL57A	6		PL81A	6	
AF32	PL57B	6		PL81B	6	
AA25	PL57C	6		PL81C	6	
AB25	PL57D	6		PL81D	6	
AJ34	PL58A	6		PL82A	6	
AK34	PL58B	6		PL82B	6	
AB27	PL58C	6		PL82C	6	
AC27	PL58D	6		PL82D	6	
AF33	PL60A	6		PL84A	6	
AG33	PL60B	6		PL84B	6	
AC29	PL60C	6		PL84C	6	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C2	VCCJ	-		VCCJ	-	
M9	TDO	-	TDO	TDO	-	TDO
L9	TMS	-		TMS	-	
D1	TCK	-		TCK	-	
C1	TDI	-		TDI	-	
J8	PROGRAMN	1		PROGRAMN	1	
K8	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
B2	CCLK	1		CCLK	1	
H9	RESP_URC	-		RESP_URC	-	
H10	VCC12	-		VCC12	-	
H8	A_REFCLKN_R	-		A_REFCLKN_R	-	
G8	A_REFCLKP_R	-		A_REFCLKP_R	-	
C3	VCC12	-		VCC12	-	
D3	A_VDDIB0_R	-		A_VDDIB0_R	-	
A3	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
B3	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
E5	VCC12	-		VCC12	-	
A4	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
F6	A_VDDOB0_R	-		A_VDDOB0_R	-	
B4	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
F7	A_VDDOB1_R	-		A_VDDOB1_R	-	
B5	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
E6	VCC12	-		VCC12	-	
A5	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
B6	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
A6	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
C6	VCC12	-		VCC12	-	
D4	A_VDDIB1_R	-		A_VDDIB1_R	-	
C7	VCC12	-		VCC12	-	
D5	A_VDDIB2_R	-		A_VDDIB2_R	-	
A7	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
B7	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
E7	VCC12	-		VCC12	-	
A8	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
F8	A_VDDOB2_R	-		A_VDDOB2_R	-	
B8	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
F9	A_VDDOB3_R	-		A_VDDOB3_R	-	
B9	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
E8	VCC12	-		VCC12	-	
A9	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
B10	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
A10	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
C10	VCC12	-		VCC12	-	
D6	A_VDDIB3_R	-		A_VDDIB3_R	-	
G10	VCC12	-		VCC12	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
F25	B_HDINN0_L	-	PCS 361 CH 0 IN N
E25	B_HDINP0_L	-	PCS 361 CH 0 IN P
D28	B_VDDIB0_L	-	
G25	VCC12	-	
D29	A_VDDIB3_L	-	
C25	VCC12	-	
A25	A_HDINP3_L	-	PCS 360 CH 3 IN P
B25	A_HDINN3_L	-	PCS 360 CH 3 IN N
A26	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
E27	VCC12	-	
B26	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
F26	A_VDDOB3_L	-	
B27	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
F27	A_VDDOB2_L	-	
A27	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
E28	VCC12	-	
B28	A_HDINN2_L	-	PCS 360 CH 2 IN N
A28	A_HDINP2_L	-	PCS 360 CH 2 IN P
D30	A_VDDIB2_L	-	
C28	VCC12	-	
D31	A_VDDIB1_L	-	
C29	VCC12	-	
A29	A_HDINP1_L	-	PCS 360 CH 1 IN P
B29	A_HDINN1_L	-	PCS 360 CH 1 IN N
A30	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
E29	VCC12	-	
B30	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
F28	A_VDDOB1_L	-	
B31	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
F29	A_VDDOB0_L	-	
A31	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
E30	VCC12	-	
B32	A_HDINN0_L	-	PCS 360 CH 0 IN N
A32	A_HDINP0_L	-	PCS 360 CH 0 IN P
D32	A_VDDIB0_L	-	
C32	VCC12	-	
E34	PL30A	7	
F34	PL30B	7	
F33	PL34A	7	
G33	PL34B	7	
K30	PL38A	7	
L30	PL38B	7	
G34	PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P38	PL26B	7		PL40B	7	
N35	PL26C	7		PL40C	7	
N36	PL26D	7		PL40D	7	
N39	PL29A	7		PL43A	7	
P39	PL29B	7		PL43B	7	
R34	PL29C	7	VREF1_7	PL43C	7	VREF1_7
T34	PL29D	7	DIFFR_7	PL43D	7	DIFFR_7
L41	PL30A	7		PL44A	7	
M41	PL30B	7		PL44B	7	
W29	PL30C	7		PL44C	7	
Y29	PL30D	7		PL44D	7	
L42	PL31A	7		PL45A	7	
M42	PL31B	7		PL45B	7	
U32	PL31C	7		PL45C	7	
V32	PL31D	7		PL45D	7	
R37	PL33A	7		PL47A	7	
T37	PL33B	7		PL47B	7	
M36	PL33C	7		PL47C	7	
M37	PL33D	7		PL47D	7	
P40	PL34A	7		PL48A	7	
N40	PL34B	7		PL48B	7	
R35	PL34C	7		PL48C	7	
T35	PL34D	7		PL48D	7	
N41	PL35A	7		PL49A	7	
P41	PL35B	7		PL49B	7	
V33	PL35C	7		PL49C	7	
U33	PL35D	7		PL49D	7	
R38	PL37A	7		PL51A	7	
T38	PL37B	7		PL51B	7	
R36	PL37C	7		PL51C	7	
T36	PL37D	7		PL51D	7	
N42	PL38A	7		PL52A	7	
P42	PL38B	7		PL52B	7	
Y31	PL38C	7		PL52C	7	
AA31	PL38D	7		PL52D	7	
U37	PL39A	7		PL53A	7	
V37	PL39B	7		PL53B	7	
U34	PL39C	7		PL53C	7	
V34	PL39D	7		PL53D	7	
U39	PL41A	7		PL55A	7	
T39	PL41B	7		PL55B	7	
V35	PL41C	7		PL55C	7	
W35	PL41D	7		PL55D	7	
R41	PL42A	7		PL56A	7	
T41	PL42B	7		PL56B	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AD33	PL59D	6		PL73D	6	
AA38	PL60A	6		PL74A	6	
AB38	PL60B	6		PL74B	6	
AC29	PL60C	6		PL74C	6	
AD29	PL60D	6		PL74D	6	
AA41	PL61A	6		PL75A	6	
AB41	PL61B	6		PL75B	6	
AC34	PL61C	6		PL75C	6	
AD34	PL61D	6		PL75D	6	
AA42	PL63A	6		PL77A	6	
AB42	PL63B	6		PL77B	6	
AC37	PL63C	6		PL77C	6	
AD37	PL63D	6		PL77D	6	
AC38	PL64A	6		PL78A	6	
AD38	PL64B	6		PL78B	6	
AD36	PL64C	6		PL78C	6	
AE36	PL64D	6		PL78D	6	
AC39	PL65A	6		PL79A	6	
AD39	PL65B	6		PL79B	6	
AD35	PL65C	6		PL79C	6	
AE35	PL65D	6		PL79D	6	
AC40	PL67A	6		PL81A	6	
AD40	PL67B	6		PL81B	6	
AE37	PL67C	6		PL81C	6	
AF37	PL67D	6		PL81D	6	
AC41	PL68A	6		PL82A	6	
AD41	PL68B	6		PL82B	6	
AE34	PL68C	6		PL82C	6	
AF34	PL68D	6		PL82D	6	
AC42	PL69A	6		PL83A	6	
AD42	PL69B	6		PL83B	6	
AE33	PL69C	6		PL83C	6	
AF33	PL69D	6		PL83D	6	
AE38	PL72A	6		PL86A	6	
AF38	PL72B	6		PL86B	6	
AE32	PL72C	6		PL86C	6	
AF32	PL72D	6		PL86D	6	
AE41	PL73A	6		PL87A	6	
AF41	PL73B	6		PL87B	6	
AE31	PL73C	6		PL87C	6	
AF31	PL73D	6		PL87D	6	
AE42	PL74A	6		PL88A	6	
AF42	PL74B	6		PL88B	6	
AG37	PL74C	6		PL88C	6	
AH37	PL74D	6		PL88D	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
A26	D_HDOUTN2_L	-	PCS 363 CH 2 OUT N	D_HDOUTN2_L	-	PCS 363 CH 2 OUT N
C34	D_VDDOB2_L	-		D_VDDOB2_L	-	
B26	D_HDOUTP2_L	-	PCS 363 CH 2 OUT P	D_HDOUTP2_L	-	PCS 363 CH 2 OUT P
C32	VCC12	-		VCC12	-	
E27	D_HDINN2_L	-	PCS 363 CH 2 IN N	D_HDINN2_L	-	PCS 363 CH 2 IN N
D27	D_HDINP2_L	-	PCS 363 CH 2 IN P	D_HDINP2_L	-	PCS 363 CH 2 IN P
G25	D_VDDIB2_L	-		D_VDDIB2_L	-	
F29	VCC12	-		VCC12	-	
H26	D_VDDIB1_L	-		D_VDDIB1_L	-	
F30	VCC12	-		VCC12	-	
D28	D_HDINP1_L	-	PCS 363 CH 1 IN P	D_HDINP1_L	-	PCS 363 CH 1 IN P
E28	D_HDINN1_L	-	PCS 363 CH 1 IN N	D_HDINN1_L	-	PCS 363 CH 1 IN N
B27	D_HDOUTP1_L	-	PCS 363 CH 1 OUT P	D_HDOUTP1_L	-	PCS 363 CH 1 OUT P
F36	VCC12	-		VCC12	-	
A27	D_HDOUTN1_L	-	PCS 363 CH 1 OUT N	D_HDOUTN1_L	-	PCS 363 CH 1 OUT N
F35	D_VDDOB1_L	-		D_VDDOB1_L	-	
A28	D_HDOUTN0_L	-	PCS 363 CH 0 OUT N	D_HDOUTN0_L	-	PCS 363 CH 0 OUT N
M30	D_VDDOB0_L	-		D_VDDOB0_L	-	
B28	D_HDOUTP0_L	-	PCS 363 CH 0 OUT P	D_HDOUTP0_L	-	PCS 363 CH 0 OUT P
F37	VCC12	-		VCC12	-	
E29	D_HDINN0_L	-	PCS 363 CH 0 IN N	D_HDINN0_L	-	PCS 363 CH 0 IN N
D29	D_HDINP0_L	-	PCS 363 CH 0 IN P	D_HDINP0_L	-	PCS 363 CH 0 IN P
H27	D_VDDIB0_L	-		D_VDDIB0_L	-	
G28	VCC12	-		VCC12	-	
J28	C_REFCLKP_L	-		C_REFCLKP_L	-	
K28	C_REFCLKN_L	-		C_REFCLKN_L	-	
F32	VCC12	-		VCC12	-	
G29	C_VDDIB3_L	-		C_VDDIB3_L	-	
C31	VCC12	-		VCC12	-	
D30	C_HDINP3_L	-	PCS 362 CH 3 IN P	C_HDINP3_L	-	PCS 362 CH 3 IN P
E30	C_HDINN3_L	-	PCS 362 CH 3 IN N	C_HDINN3_L	-	PCS 362 CH 3 IN N
B29	C_HDOUTP3_L	-	PCS 362 CH 3 OUT P	C_HDOUTP3_L	-	PCS 362 CH 3 OUT P
F38	VCC12	-		VCC12	-	
A29	C_HDOUTN3_L	-	PCS 362 CH 3 OUT N	C_HDOUTN3_L	-	PCS 362 CH 3 OUT N
J33	C_VDDOB3_L	-		C_VDDOB3_L	-	
A30	C_HDOUTN2_L	-	PCS 362 CH 2 OUT N	C_HDOUTN2_L	-	PCS 362 CH 2 OUT N
K33	C_VDDOB2_L	-		C_VDDOB2_L	-	
B30	C_HDOUTP2_L	-	PCS 362 CH 2 OUT P	C_HDOUTP2_L	-	PCS 362 CH 2 OUT P
J34	VCC12	-		VCC12	-	
F31	C_HDINN2_L	-	PCS 362 CH 2 IN N	C_HDINN2_L	-	PCS 362 CH 2 IN N
E31	C_HDINP2_L	-	PCS 362 CH 2 IN P	C_HDINP2_L	-	PCS 362 CH 2 IN P
G30	C_VDDIB2_L	-		C_VDDIB2_L	-	
H28	VCC12	-		VCC12	-	
C37	C_VDDIB1_L	-		C_VDDIB1_L	-	
H30	VCC12	-		VCC12	-	

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1101 - Power Estimation and Management for LatticeSC Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Industrial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-6F256I	-6	fpBGA	256	IND	15.2
LFSC3GA15E-5F256I	-5	fpBGA	256	IND	15.2
LFSC3GA15E-6F900I	-6	fpBGA	900	IND	15.2
LFSC3GA15E-5F900I	-5	fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-6F256I	-6	fpBGA	256	IND	15.2
LFSCM3GA15EP1-5F256I	-5	fpBGA	256	IND	15.2
LFSCM3GA15EP1-6F900I	-6	fpBGA	900	IND	15.2
LFSCM3GA15EP1-5F900I	-5	fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-6F900I	-6	fpBGA	900	IND	25.4
LFSC3GA25E-5F900I	-5	fpBGA	900	IND	25.4
LFSC3GA25E-6FF1020I[1]	-6	Organic fcBGA	1020	IND	25.4
LFSC3GA25E-5FF1020I[1]	-5	Organic fcBGA	1020	IND	25.4
LFSC3GA25E-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	25.4
LFSC3GA25E-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-6F900I	-6	fpBGA	900	IND	25.4
LFSCM3GA25EP1-5F900I	-5	fpBGA	900	IND	25.4
LFSCM3GA25EP1-6FF1020I[1]	-6	Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-5FF1020I[1]	-5	Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	25.4
LFSCM3GA25EP1-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-6FF1020I[1]	-6	Organic fcBGA	1020	IND	40.4
LFSC3GA40E-5FF1020I[1]	-5	Organic fcBGA	1020	IND	40.4
LFSC3GA40E-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-6FC1152I[2]	-6	Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-5FC1152I[2]	-5	Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-6FF1152I	-6	Organic fcBGA	1152	IND	40.4
LFSC3GA40E-5FF1152I	-5	Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.